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(12) **United States Design Patent**
Majima et al.

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(45) **Date of Patent: ** Dec. 29, 2020**

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(54) **SEMICONDUCTOR DEVICE**

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(73) Assignee: **ROHM CO., LTD.**, Kyoto (JP)

(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D10/80, 103; D13/110, 133, 139, 154, D13/173, 182; D14/217, 432, 433
CPC H01L 20/4238; H01L 23/528; H01L 29/0696; H01L 29/1095; H01L 29/417; H01L 29/66068; H01L 29/1608; H01L 29/7395; H01L 29/7802; H01L 29/66325; H01L 29/66348; H01L 29/161; H01L 29/162; H01L 29/163; H01L 29/164; H01L 29/165; H01L 29/166; H01L 29/167; H01L 21/18; H01L 21/19; H01L 21/20; H01L 21/21; H01L 21/22; H01L 21/23; H01L 21/24; H01L 21/25; H01L 21/26; H01L 21/27; H01L 21/28; H01L 21/29; H01L 21/30
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. **1** is a front, bottom and right side perspective view of a semiconductor device showing our new design;
FIG. **2** is a front view thereof;
FIG. **3** is a top plan view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is an enlarged view of a portion indicated by line 5-5 in FIG. **1**; and,
FIG. **6** is an enlarged cross-sectional view taken along line 6-6 in FIG. **2** showing a portion indicated by lines 6-6 in FIG. **4**.
The broken lines illustrate portions of the semiconductor device that form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design.

1 Claim, 6 Drawing Sheets

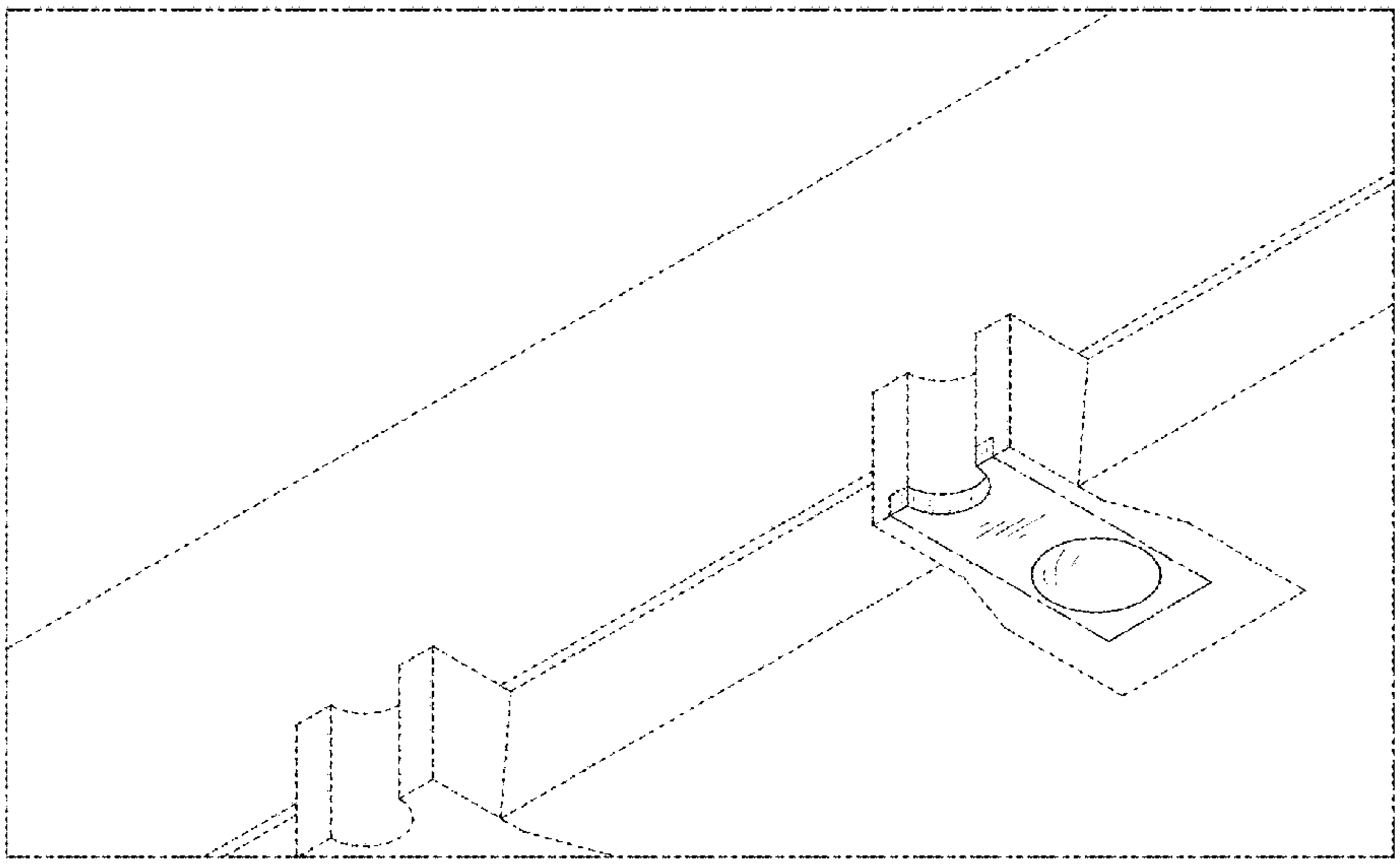

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FIG. 1

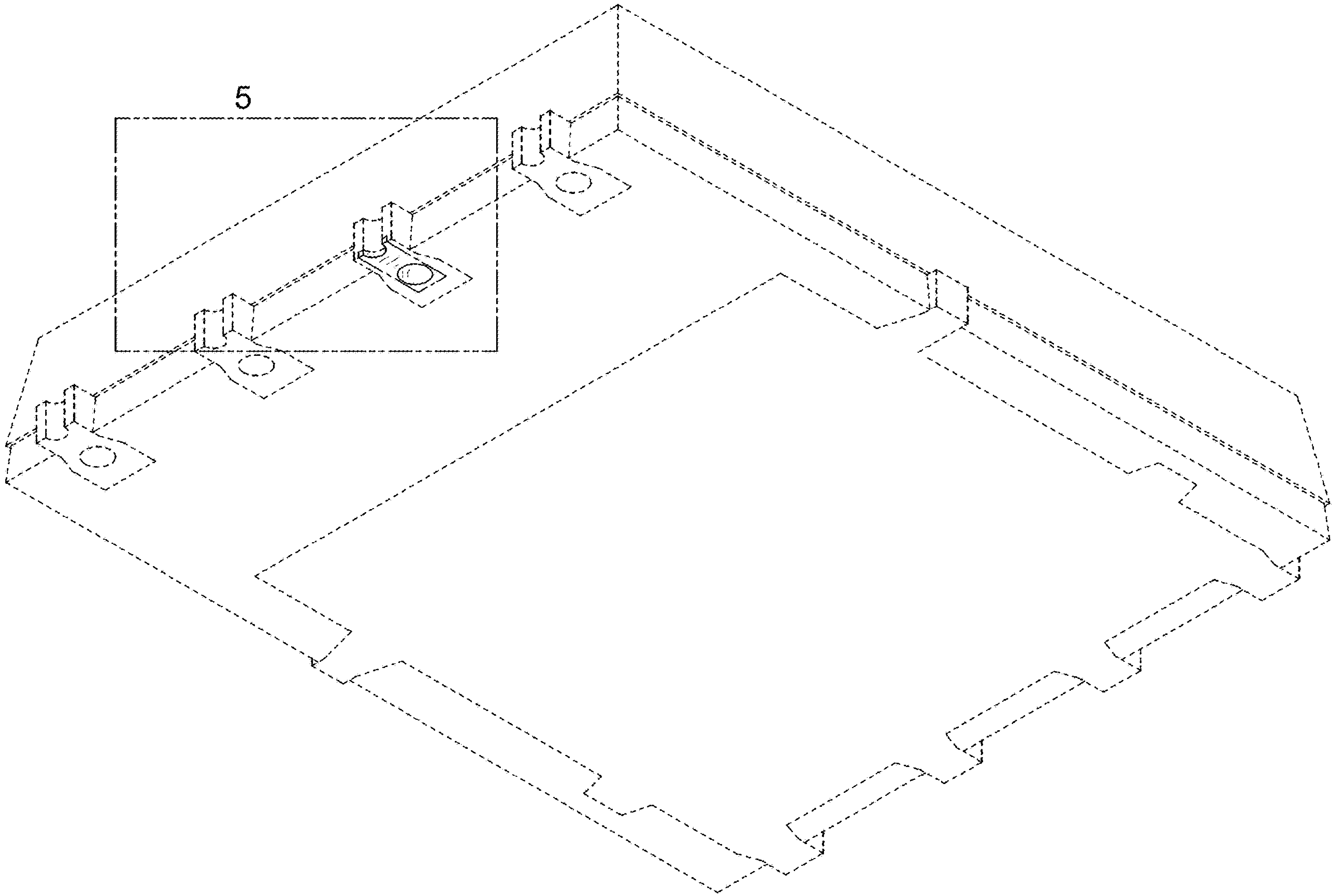

FIG.2

FIG.3

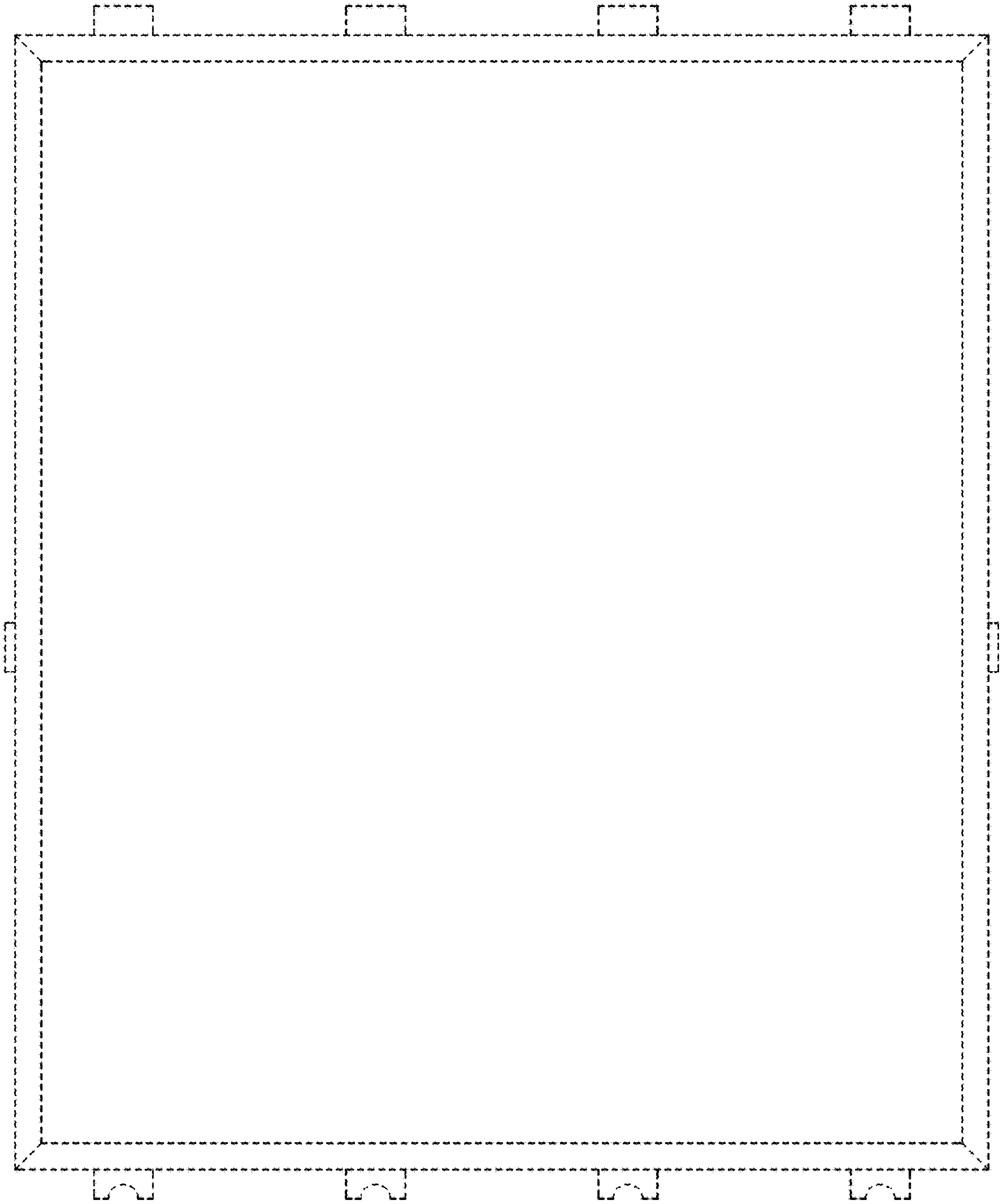

FIG.4

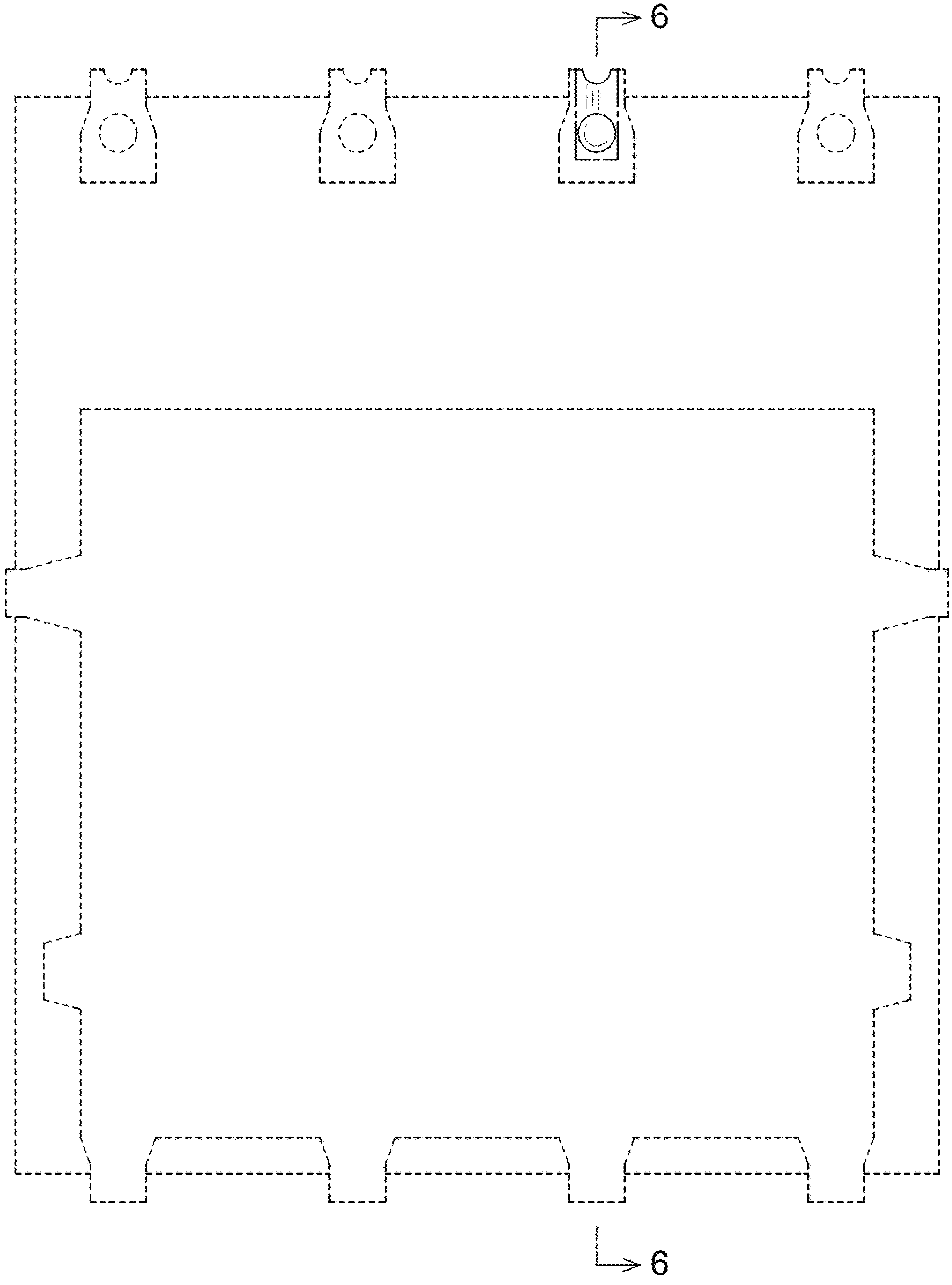

FIG.5

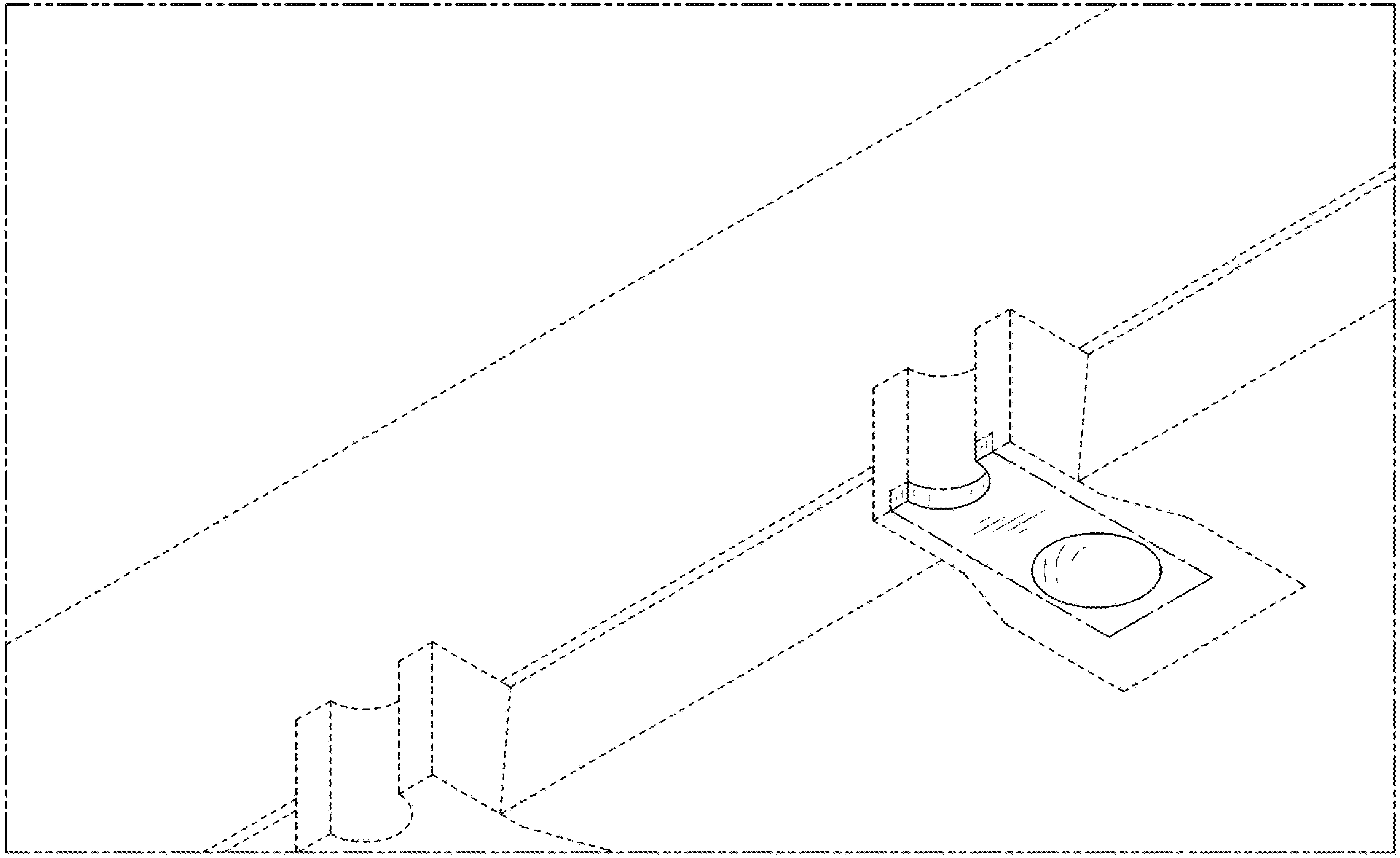

FIG.6